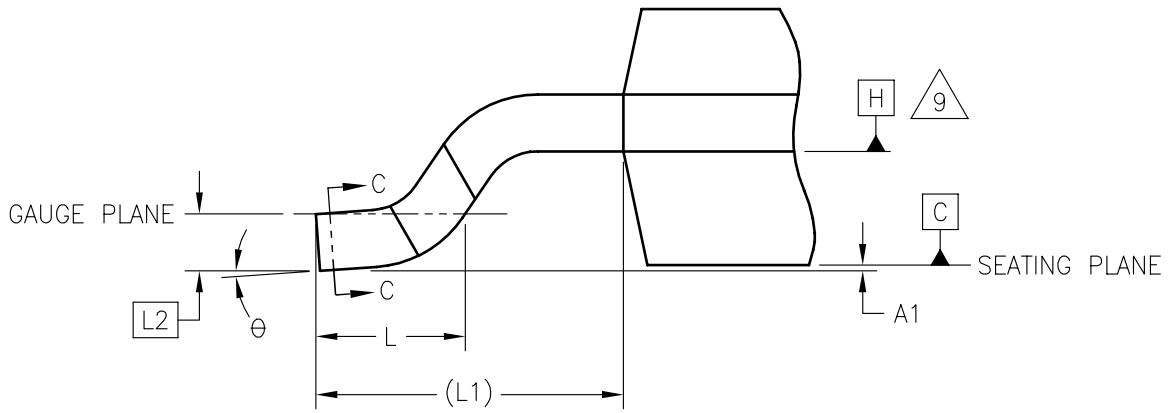


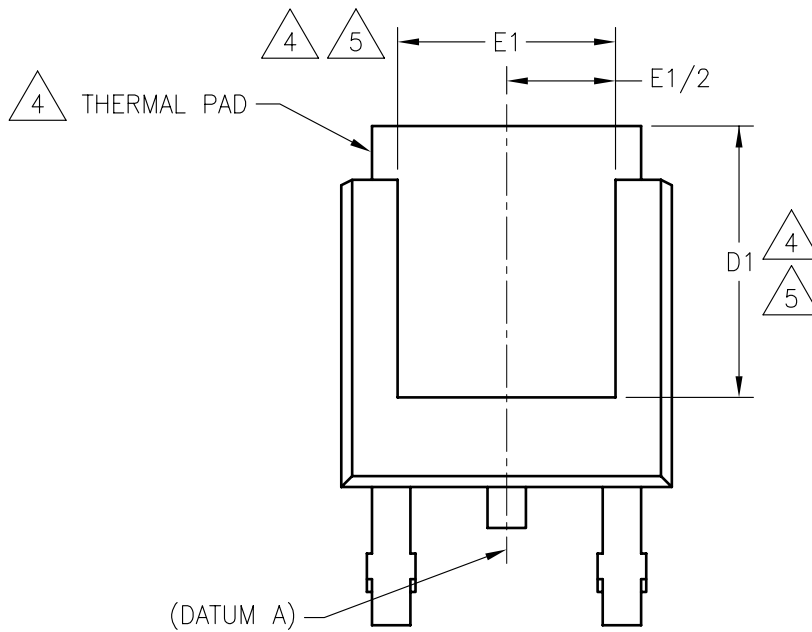
JEDEC
SOLID STATE
PRODUCT OUTLINE

THIS **REGISTERED OUTLINE** HAS BEEN PREPARED BY THE JEDEC JC-11 COMMITTEE AND REFLECTS A PRODUCT WITH ANTICIPATED USAGE IN THE ELECTRONICS INDUSTRY; CHANGES ARE LIKELY TO OCCUR.

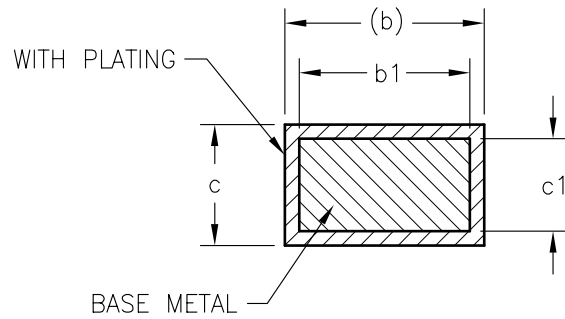
TITLE	2 LEAD HEADER FAMILY SURFACE MOUNTED (PERIPHERAL TERMINALS)	PACKAGE DESIGNATOR	ISSUE	DATE	SHEET
	R-PSFM-G	C	11/99	T0-252	1 OF 4



VIEW B
ROTATED 90° CW



VIEW A-A



SECTION C-C



<p>JEDEC SOLID STATE PRODUCT OUTLINE</p>	<p>TITLE 2 LEAD HEADER FAMILY SURFACE MOUNTED (PERIPHERAL TERMINALS)</p>	<p>ISSUE C</p>	<p>DATE 11/99</p>	<p>TO-252</p>	<p>SHEET 2 OF 4</p>
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VARIATIONS (ALL DIMENSIONS SHOWN IN INCHES)

SYMBOL	AA			NOTES	AB			NOTES	AC			NOTES
	MIN	NOM	MAX		MIN	NOM	MAX		MIN	NOM	MAX	
A	.086	—	.094		.086	—	.094		.070	—	.080	
A1	—	—	.005		—	—	.005		0	.002	.005	
b	.025	—	.035	6	.025	—	.035	6	.025	—	.035	6
b1	.025	.028	.031	6	.025	.028	.031	6	.025	.028	.031	6
b2	.030	—	.045		.030	—	.045		.025	—	.035	
b3	.205	.210	.215	4	.205	.210	.215	4	.218	.223	.228	4
c	.018	—	.024	6	.018	—	.024	6	.007	—	.015	6
c1	.018	.020	.022	6	.018	.020	.022	6	.007	.010	.013	6
c2	.018	—	.023	6	.018	—	.023	6	.007	—	.015	6
D	.235	.240	.245	7,8	.210	.215	.220	7,8	.237	.242	.247	7,8
D1	.205	—	—	4,5	.180	—	—	4,5	.160	—	—	4,5
E	.250	—	.265	7,8	.250	—	.265	7,8	.233	—	.243	7,8
E1	.170	—	—	4,5	.150	—	—	4,5	.080	—	—	4,5
e	.090 BSC				.090 BSC				.090 BSC			
H	.370	—	.410		.370	—	.410		.370	—	.390	
L	.055	.060	.070		.055	.060	.070		.037	.042	.047	
L1	.108 REF				.105 REF				.098 REF			
L2	.020 BSC				.020 BSC				.010 BSC			
L3	.035	—	.050	4	.060	—	.080	4	.030	—	.050	4
L4	.025	—	.040		.025	—	.040		—	—	.030	
L5	.045	—	.060	3	.045	—	.060	3	NA	NA	NA	
θ	0°	—	10°		0°	—	8°		0°	—	8°	
θ1	0°	—	15°		0°	—	15°		0°	—	15°	
N	2				2				2			
NOTES	1,2				1,2				1,2			
REF	10-209/10-394				10-268/10-394				10-394			
ISSUE	A/C				B/C				C			

NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M-1994.

2. DIMENSIONS IN INCHES.



LEAD DIMENSION UNCONTROLLED IN L5.



THERMAL PAD CONTOUR OPTIONAL WITHIN DIMENSIONS b3 AND L3, AND D1 AND E1.



DIMENSIONS D1 AND E1 ESTABLISH A MINIMUM MOUNTING SURFACE FOR THERMAL PAD.



SECTION C-C DIMENSIONS APPLY TO THE FLAT SECTION OF THE LEAD BETWEEN .005 AND .010 INCHES FROM THE LEAD TIP.



DIMENSION D DOES NOT INCLUDE INTERLEAD FLASH OR PROTRUSION. INTERLEAD INTERLEAD FLASH OR PROTRUSION SHALL NOT EXCEED .006 INCHES PER END. DIMENSION E DOES NOT INCLUDE MOLD FLASH, PROTRUSIONS OR GATE BURRS. MOLD FLASH, PROTRUSIONS OR GATE BURRS SHALL NOT EXCEED .006 INCHES PER SIDE.



THE PACKAGE TOP MAY BE SMALLER THAN THE PACKAGE BOTTOM. DIMENSIONS D AND E ARE DETERMINED AT THE OUTERMOST EXTREMES OF THE PLASTIC BODY EXCLUSIVE OF MOLD FLASH, TIE BAR BURRS, GATE BURRS AND INTERLEAD FLASH, BUT INCLUDING ANY MISMATCH BETWEEN THE TOP AND BOTTOM OF THE PLASTIC BODY.



DATUMS A AND B TO BE DETERMINED AT DATUM PLANE H.

JEDEC SOLID STATE PRODUCT OUTLINE	TITLE 2 LEAD HEADER FAMILY SURFACE MOUNTED (PERIPHERAL TERMINALS)	ISSUE C	DATE 11/99	TO-252	SHEET 4 OF 4
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